

40. (New) The method of claim 35, wherein the step of filling the solder resister or resin comprises;

B1 a first step of plugging the solder resist or insulating resin in one portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole; and

a second step of completely plugging the solder resist or insulating resin in the whole portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole.

41. (New) The method of claim 40, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the opposite direction to the moving direction of the squeegee in the first plugging step.

42. (New) The method of claim 40, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the same direction to the moving direction of the squeegee in the first plugging step.

43. (New) The method of claim 35, wherein the solder resist or insulating resin is coated only on an area exposed by a mask for selectively exposing the plurality of circuit patterns formed on the printed circuit board at a predetermined interval or on the hole.

44. (New) The method of claim 35, wherein the solder resist or insulating resin filled in the spaces among the surface

side circuit patterns is filled to the same height as the upper surface of the circuit patterns.

45. (New) The method of claim 37, wherein the solder resist or insulating resin is plugged into the hole by moving the squeegee under the condition of being abutted directly on the upper surface of the hole.

46. (New) The method of claim 37, wherein the step of filling the solder resister or resin comprises;

B1 a first step of plugging the solder resist or insulating resin in one portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole; and

a second step of completely plugging the solder resist or insulating resin in the whole portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole.

47. (New) The method of claim 46, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the opposite direction to the moving direction of the squeegee in the first plugging step.

48. (New) The method of claim 46, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the same direction to the moving direction of the squeegee in the first plugging step.

49. (New) The method of claim 37, wherein the solder resist or insulating resin is coated only on an area exposed by a

mask for selectively exposing the plurality of circuit patterns formed on the printed circuit board at a predetermined interval or on the hole.

50. (New) The method of claim 37, wherein the solder resist or insulating resin filled in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the circuit patterns.

B1 51. (New) A plugging method for a printed circuit board having a plurality of first circuit patterns formed on a surface of the board,

wherein a solder resist or insulting resin is filled in spaces between the first circuit patterns by moving a squeegee under the condition of being abutted on an upper surface of the first circuit patterns.

52. (New) The method of claim 51, wherein the printed circuit board further includes one or more via holes formed to electrically connect between the first circuit patterns and a plurality of second circuit patterns formed inside the board, and/or one or more through holes formed to electrically interconnect both the upper and lower surface of the first circuit patterns.

53. (New) The method of claims 51, wherein the solder resist or insulating resin filled in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the first circuit patterns.

54. (New) The method of claim 52, wherein the solder resister or insulting resin is plugged into the via holes and/or the through holes by moving the squeegee under the condition of being abutted directly on the upper surface of the via holes and/or the through holes.

55. (New) The method of claim 52, comprising the steps of:

61 a first step of plugging the solder resist or insulating resin in one portion of the via holes and/or the through holes; and

a second step of completely plugging the solder resister or insulating resin in the whole portion of the via holes and/or the through holes by moving the squeegee under the condition of being abutted on the surface of the via holes and/or the through holes.

56. (New) The method of claim 55, wherein in the second plugging step the solder resist or insulting resin is plugged in the via holes and/or the through holes by moving the squeegee in the opposite direction to the moving direction of the squeegee in the first plugging step.

57. (New) The method of claim 55, wherein in the second plugging step the solder resist or insulting resin is plugged in the hole by moving the squeegee in the same direction to the moving direction of the squeegee in the first plugging step.

58. (New) The method of claim 52, wherein the solder resist or insulating resin is coated only on an area exposed by a mask for selectively exposing the first circuit patterns at a

predetermined interval or on the via holes and/or the through holes.

B1 59. (New) The method of claims 52, wherein the solder resist or insulating resin filled in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the first circuit patterns.--

---